



Remedies in Design for Reliability

RadHard in SoC Design

Chun-Zhang Chen, Ph.D.

June 25-29, 2018



中国科学院大学**2018**年夏季

RadHard in SoC Design

SEE and RadHard



Cosmic Rays and Charged Particles



Cosmic Rays and Neutrons



RadHard Remedies



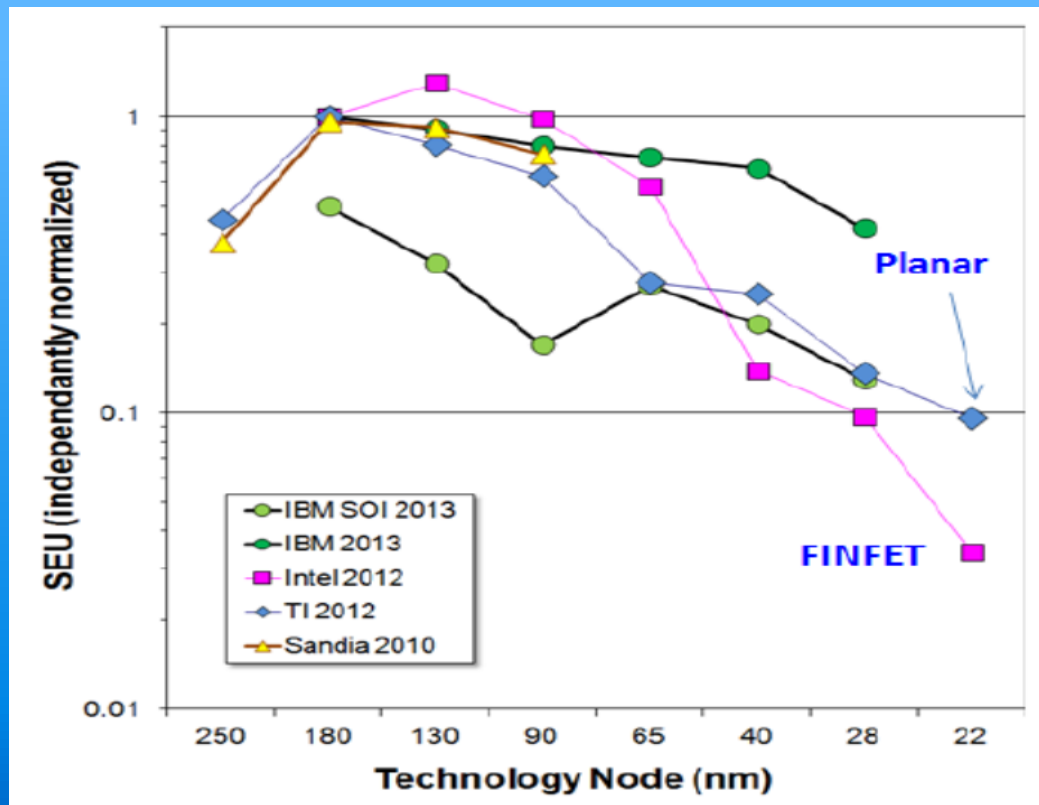
Discussion



Causes of Chip Failures and Remedies for Reliability

- Design Bugs
- Excess Temperature
- Rush Current
- Manuf. Defaults
- ESD Issues
- Verification
- Library Corners
- Electro-migration
- DFT/ATE
- ESD Protection

SEU Sensitivity for SRAM



Reported SER (or SEU) values of SRAM products

Table 5: The reported SER (or SEU) values of SRAM products influenced by various neutron fluence conditions ↵

Products	fluence	SER (SEU)	Vendor Ref. ↵
0.6um, 0-11MeV, 14MeV	$(5-86) \times 10^9$	0	Xilinx 1998 ↵
FPGA 0.35um, 100 MeV	0.3×10^9	(5)	Xilinx 1998 ↵
1Gb 130nm@3889m	3.69×10^6	(4000)	[2] 2012 ↵
2x1Gb 90nm@2885m	3.5×10^6	(3000)	[2] 2012 ↵
16Mb 65nm, 20-250MeV	$(2-3) \times 10^9$	838	Cypress 2017 ↵
Virtex-6 RAM, 40nm	$\sim 1 \times 10^9$	83	Xilinx 2009 ↵

Source: Chen & Hu, 2018, CSTIC

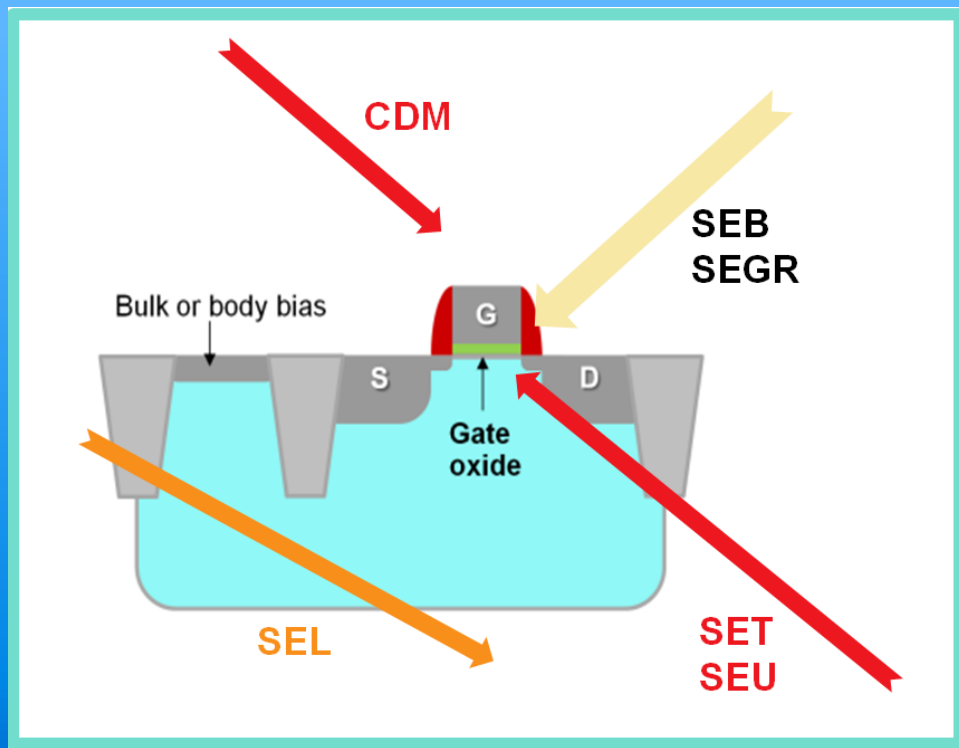
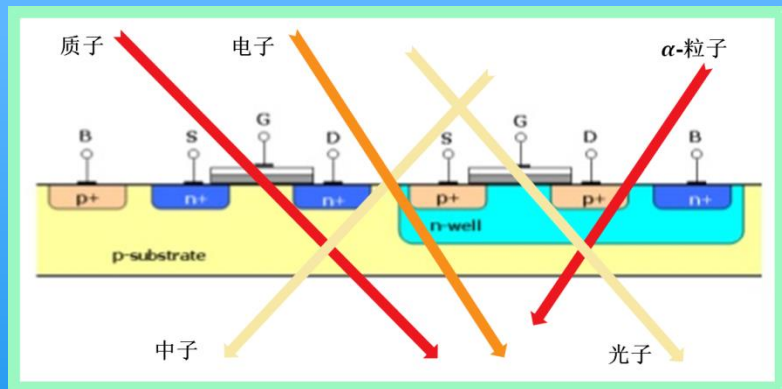
RadHard Topics

- SEE/SEU and RadHard/TID
- FPGA chips
- SRAM
- SOI
- Stopping Power and Range
- Variable factors

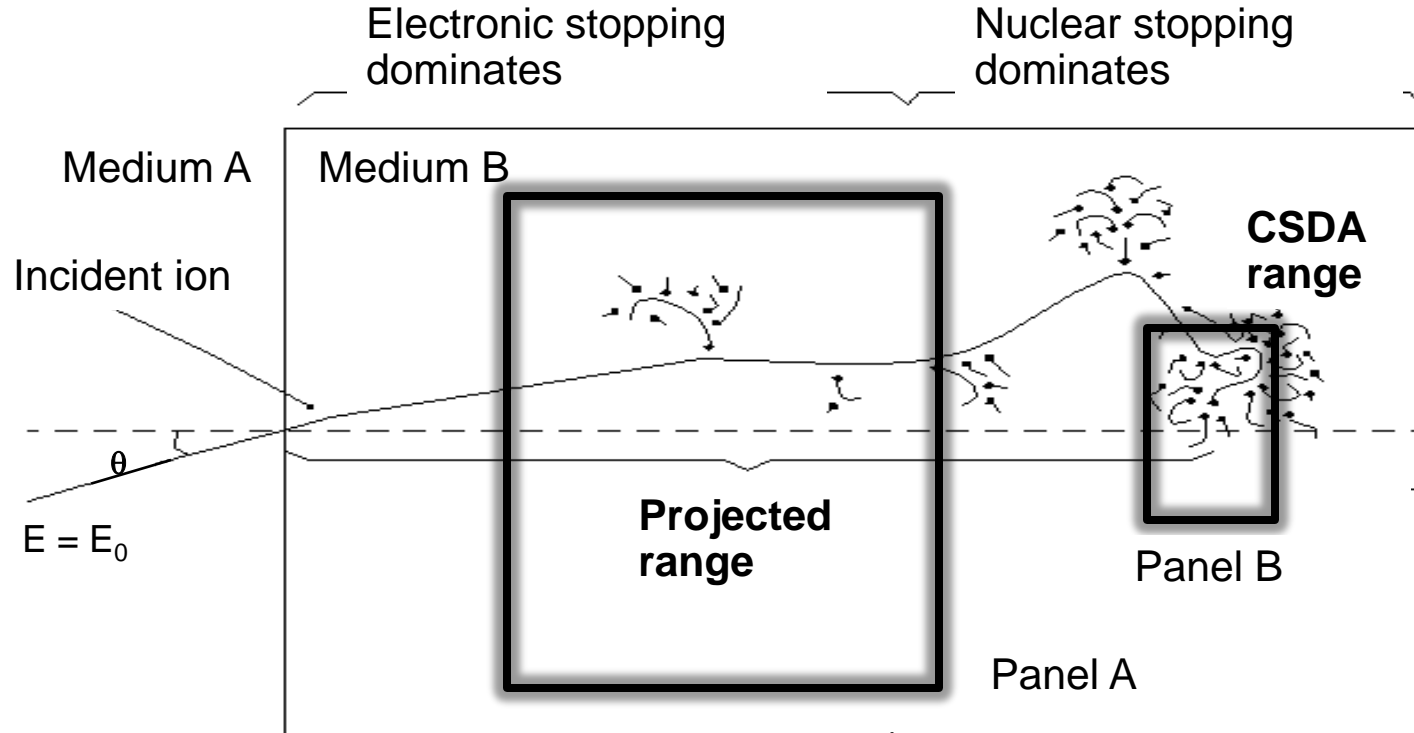
Study of Radiation-Induced Effects

- TID – total ionizing dose
- SEE – single event effects (SP/ρ)
 - *SEU, single event upset*
 - *SET, single event transient*
 - *SEL, single event latchup*
 - *SEB, single event burnout*
 - *SEGR, single event gate rupture*

ESD and SEE on Bulk CMOS, FD-SOI, FinFET

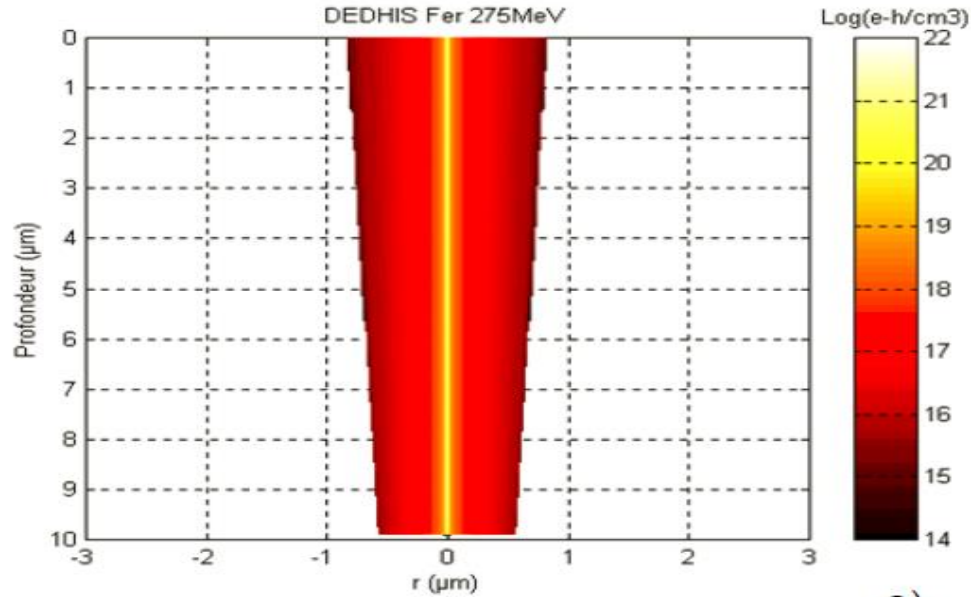


Proton Interaction and CSDA/Projected Ranges

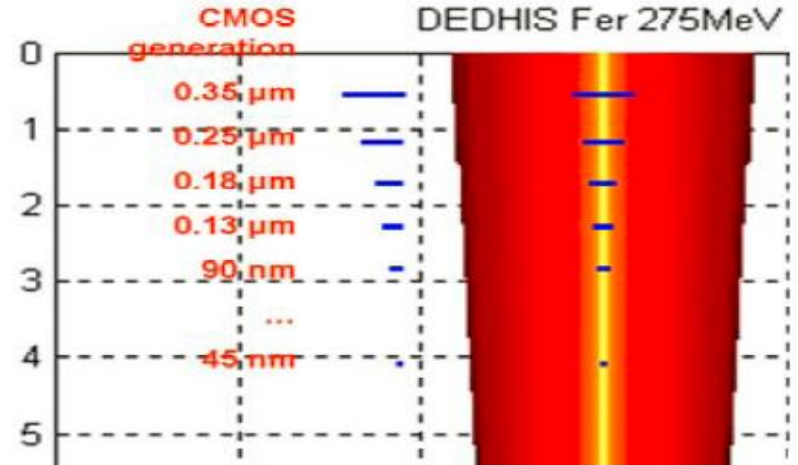


Heavy Ions Induced Secondaries and Tertiaries

Electron-Hole density (cm^{-3})



a)



b)

- a) Trajectory path of heavy ions at 275 MeV ($\text{LET} = 24 \text{ MeV-cm}^2/\text{mg}$);
- b) Comparison with CMOS node sizes (45-350 nm)

Ref.: Griffoni Alessio, 2009

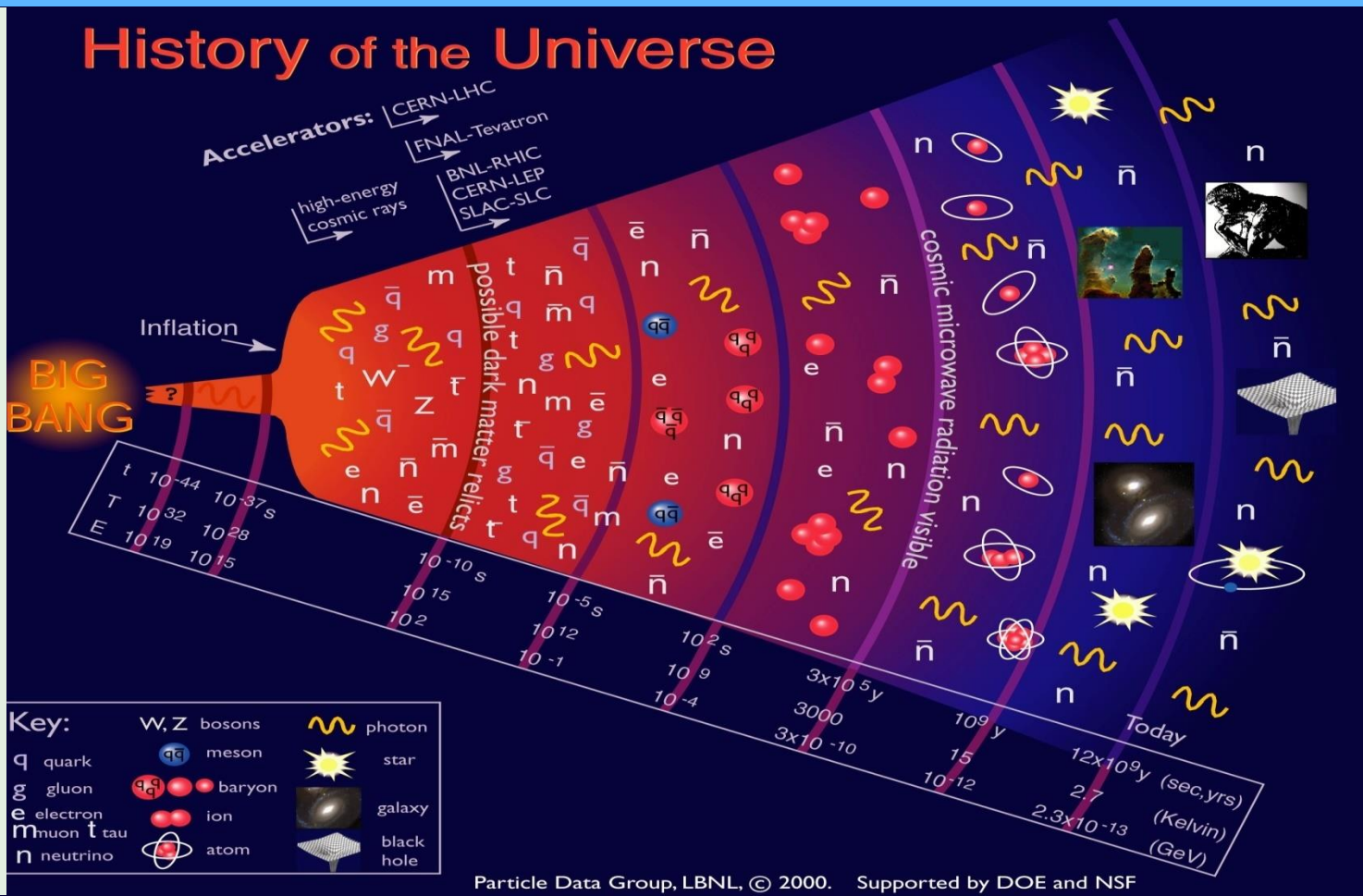
RadHard in SoC Design



- SEE and RadHard: SEE/SEU, RadHard/TID/SP
- **Cosmic Rays & Charged Particles:** p , e , α , ions
- Cosmic Rays & Neutrons: cross-section, range, fluence
- RadHard Remedies: TID, SOI
- Discussion

Big Bang Higgs Boson Supernova Van Allen Belt

... particles and their large effects ...

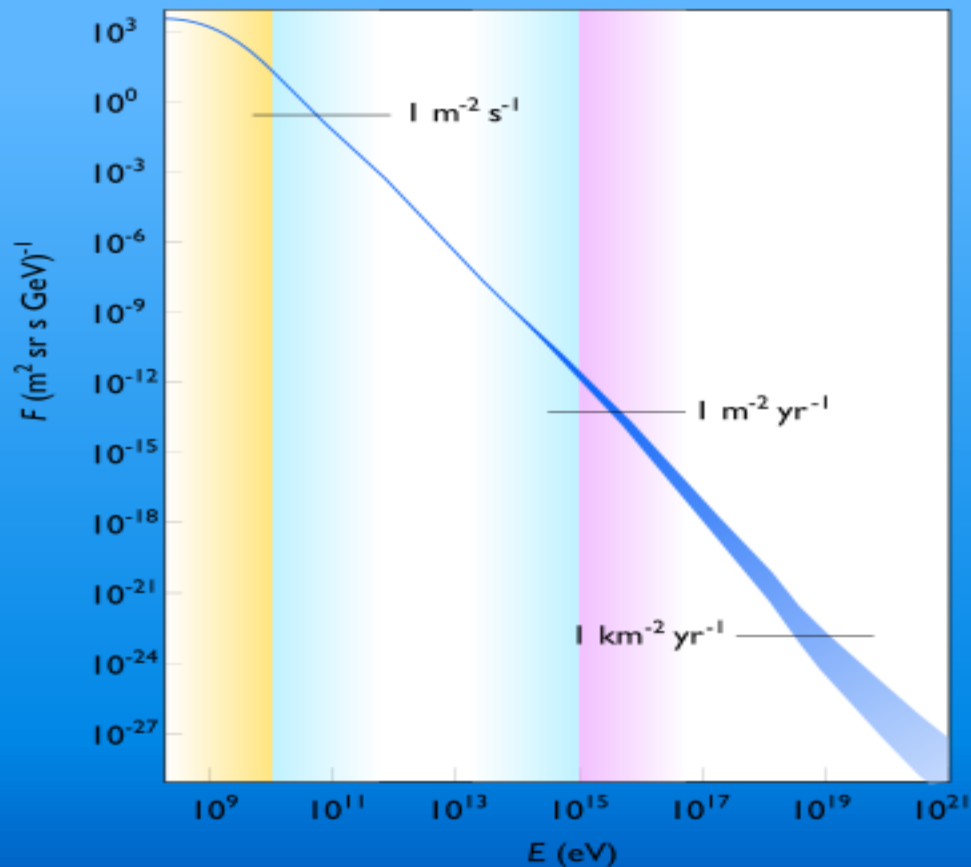


Particle Data Group, LBNL, © 2000. Supported by DOE and NSF

Gravitational Wave Observatory

- Predicted by Albert Einstein in general relativity in 1916: G-wave → G-radiation similar to EM
- LIGO, Feb 2016
 - includes more than 900 scientists worldwide, as well as
 - 44,000 active Einstein@Home users
-
- A Brief History of Humankind - Homo Sapiens

Cosmic ray – high-energy radiation



Space Radiation

● Radiation Particles in Van Allen Belts and Solar/Galactic Cosmics

Environment	Composition	Energy	Flux, $1/(\text{cm}^2 \cdot \text{s})$
Inner Van Allen belt Alt. (1,000-6,000) km	protons (99%) electrons (1%)	10-50 MeV ≥ 100 keV	$(1-2) \times 10^5$ (≥ 50 MeV) 3×10^6 (≥ 1 MeV)
Outer Van Allen belt Alt. (13,000-60,000) km	protons (1%) electrons (99%)	1 MeV (0.1-10) MeV	2×10^6
Solar/Galactic cosmics At Earth's surface	protons (90%) alphas (9%) HZE ions (1%) photons (x-, γ -)	1×10^9 (1 GeV) 1×10^{12} (1 TeV) 1×10^{16} (10 PeV) 1×10^{20} (100 EeV)	1×10^4 1×10^0 1×10^{-7} [a] 1×10^{-9} [b]
[a] a few times a year; [b] once a century			

Cosmic Rays and Ionization Radiation



- Types of Ionizing Radiation

- Charged Particles:

- p , e , α (He^4), β (e^- , e^+), ions

- Non-charged particles: n , X-rays, γ -rays

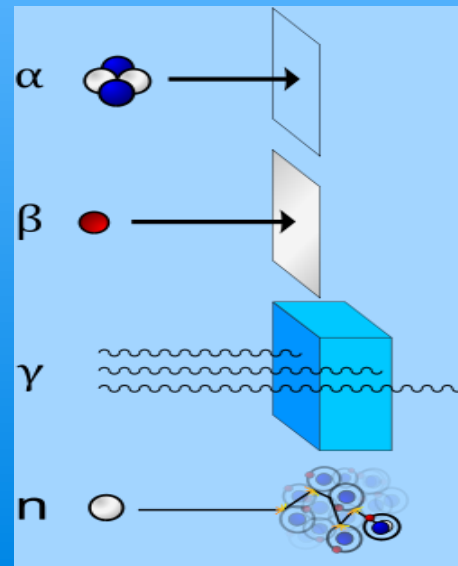
- X-rays, γ -rays are EM radiation

- Interactions of Ionizing Radiation

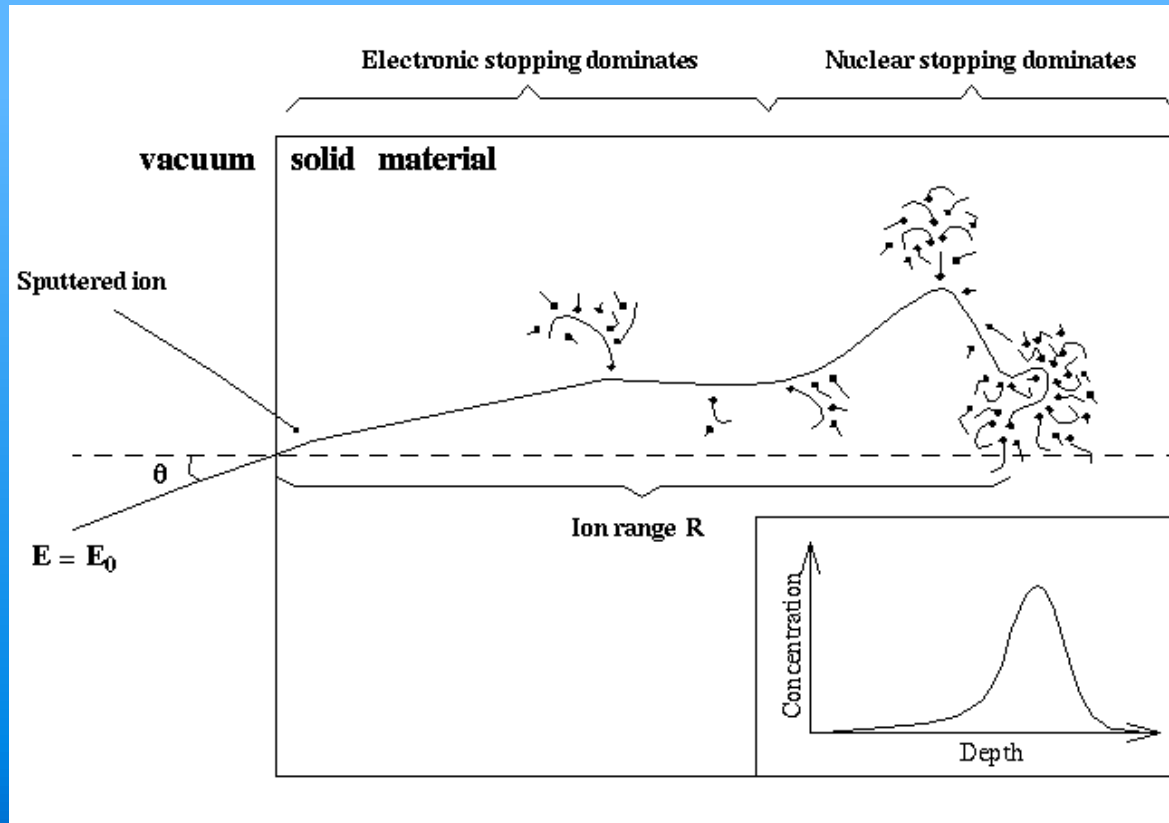
- Interaction process: Ionization events

- Ionization products

- Secondary, tertiary particles are produced

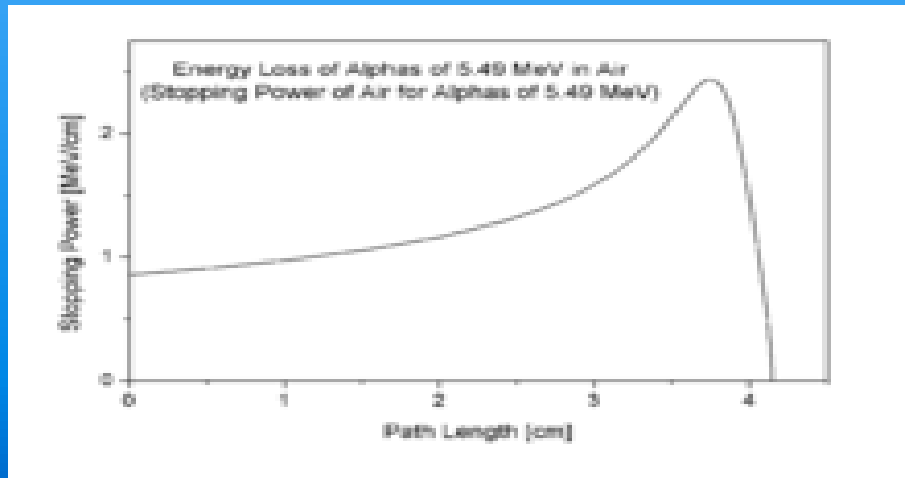
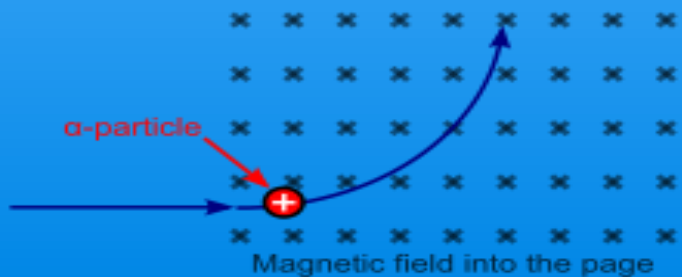
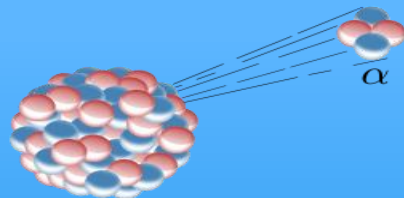


Interactions via Secondary Particles



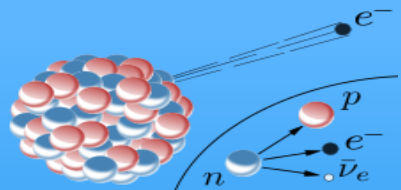
Alpha Particles – 2 protons, 2 neutrons

- Symbols: α , α^{2+} , He^{2+} , or ${}^4_2\text{H}^{2+}$
- Process: alpha decay
- In general $>5\text{MeV}$, speed is about 5% of c
- In cosmic, 10-12%



Beta Particles

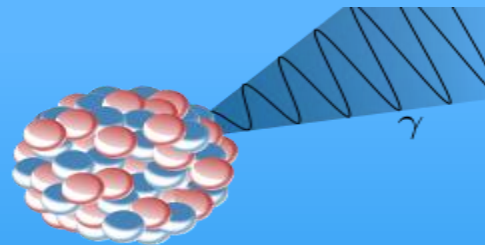
- Beta particles are either β^- or β^+
- Electron emission, β^- decay
$$n \rightarrow p + e^- + \bar{\nu}_e$$
- Positron emission, β^+ decay
$$p \rightarrow n + e^+ + \nu_e$$
- Decay via EM and may give off bremsstrahlung x-rays.
- Detection and measurement
 - ion chambers,
 - Geiger-Muller counters, and
 - scintillation counters



Blue Cherenkov radiation light being emitted from a TRIGA reactor pool is due to high speed beta particles traveling faster than the speed of light (phase velocity) in water (which is 75% of the speed of light in vacuum).

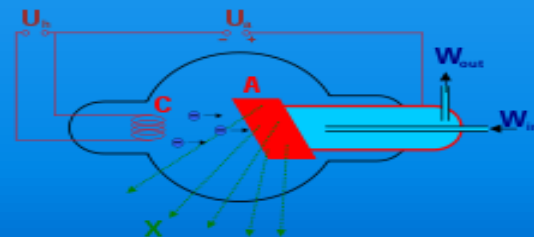
Gamma rays (Paul Villard, 1900)

- Nuclear radiation: γ -rays
 - Villard (Fr.) discovered in Radium,
 - named as γ -rays by Rutherford in 1903
- Non-nuclei γ -rays
 - from lighting strikes,
 - terrestrial γ -ray flashes
- Characteristics of γ -rays
 - $f > 10$ exahertz (or $> 10^{19}$ Hz), < 10 pm ($< 10^{-11}$ nm, or 0.1 \AA)
 - typically > 100 keV; astronomical > 10 TeV

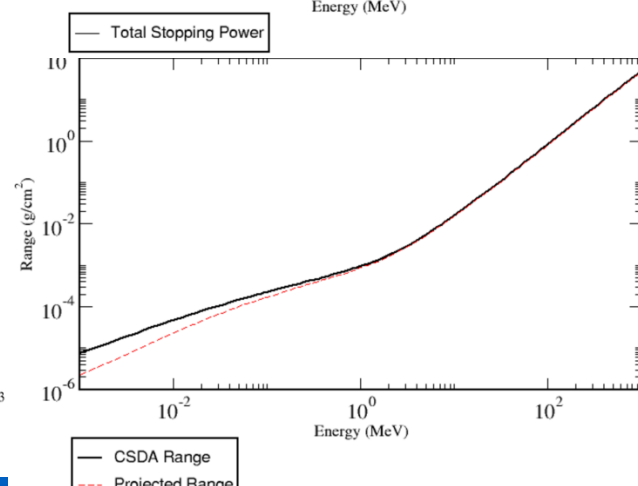
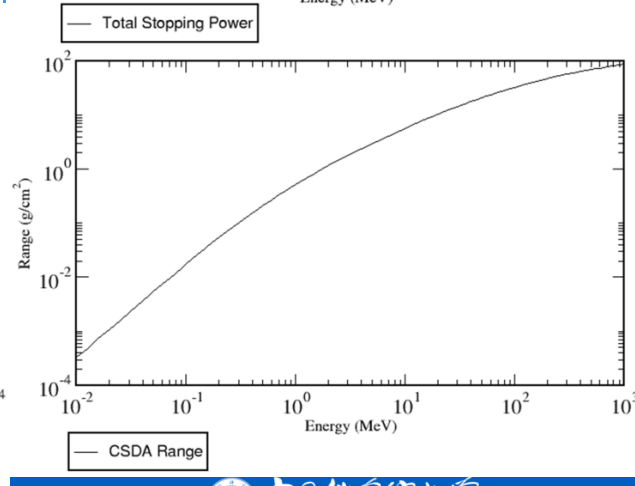
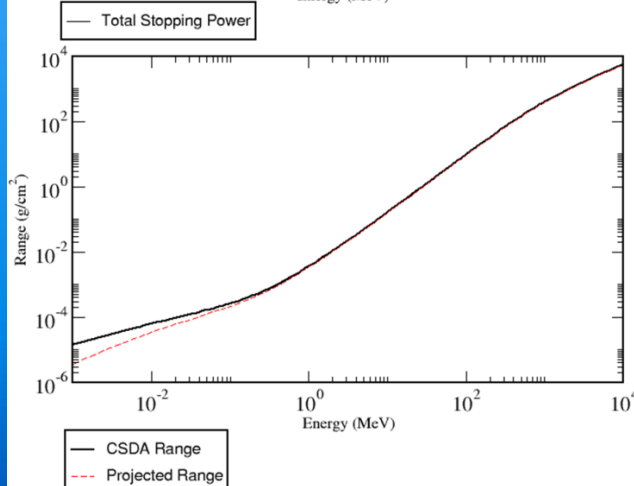
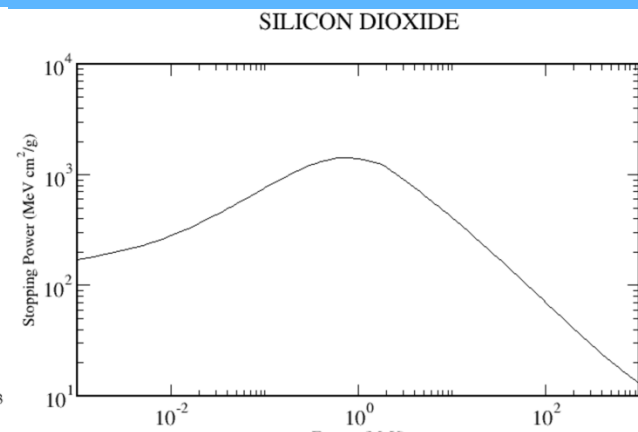
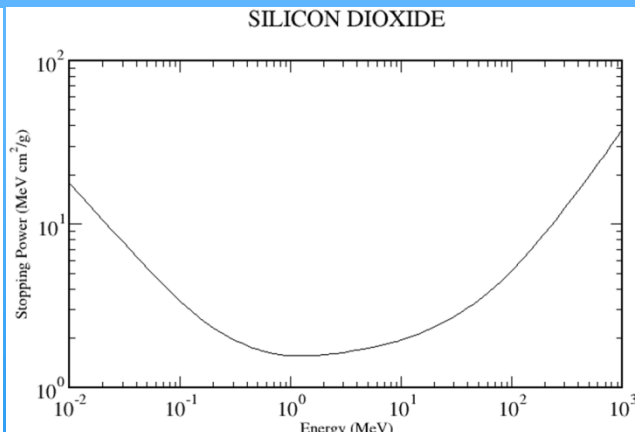
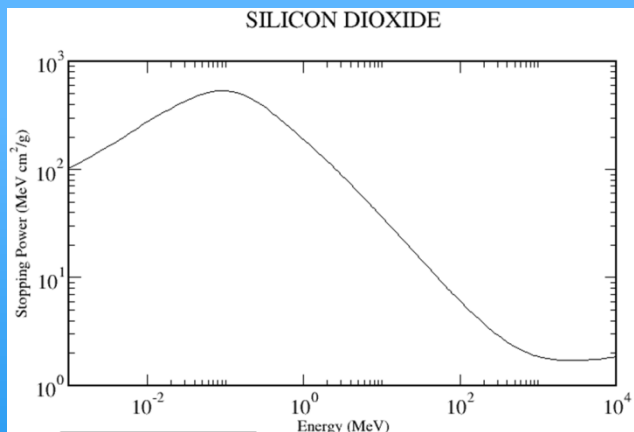


X-ray (Röntgen radiation) 1895

- 1901 The First Nobel Prize, Wilhelm Röntgen
- Characteristics of X-ray
 - wavelength 0.01-10nm (3×10^{16} Hz - 3×10^{19} Hz)
 - between UV and γ -ray
 - Energy range: 100 eV – 100 keV
 - hard X-ray >5-10 keV (0.2-0.1nm);
 - soft X-ray <5 keV
 - Medical radiotherapy;
 - linear accelerators 6-20 MeV



Selected Results of SP and Range for e, p, α Particles



RadHard in SoC Design

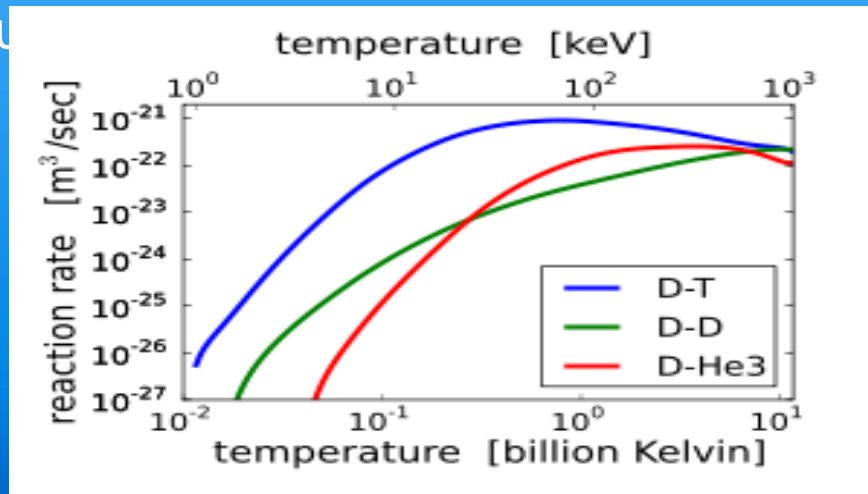
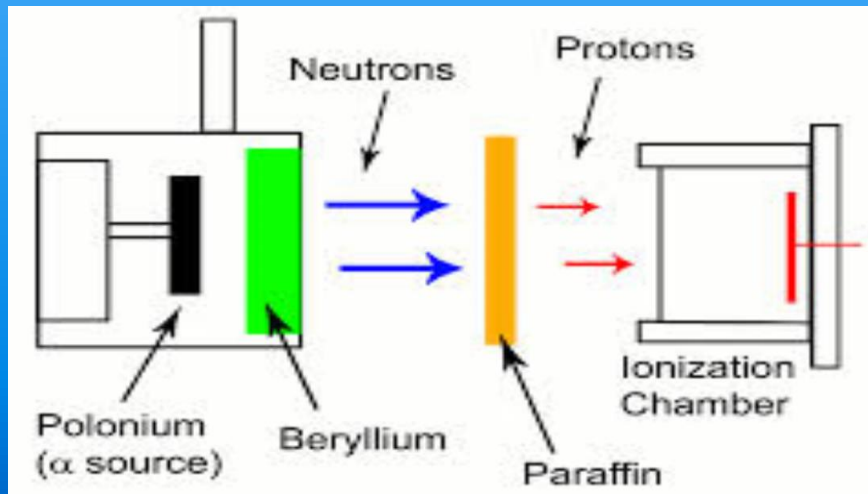


- SEE and RadHard: SEE/SEU, RadHard/TID/SP
- Cosmic Rays & Charged Particles: p , e , α , ions
- **Cosmic Rays & Neutrons:** cross-section, range, fluence
- RadHard Remedies: TID, SOI
- Discussion

Big Bang Higgs Boson Supernova Van Allen Belt

Discovery of the Neutron (1932)

- Sir James Chadwick, 1935 Physics Nobel Prize
 - Cavendish Lab., Cambridge University
- Atomic number (Z , # of p), and (atomic) mass number (A),

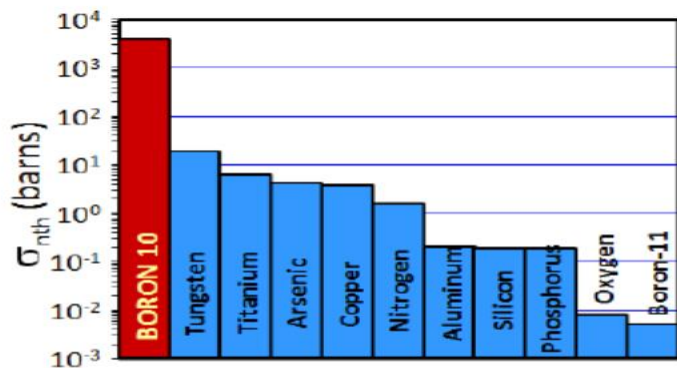


Neutron Temperature

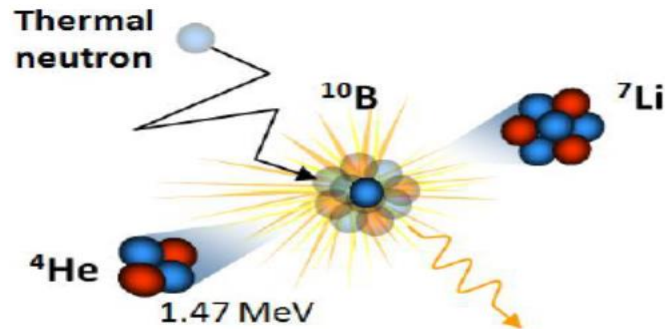
- **Thermal** neutrons, free with $kT=0.0253$ eV, speed 2.2km/s
- **Cold** neutrons, equilibrated w/ deuterium, for scattering exp.
- **Ultracold** neutrons,
 - a few kelvins w/ solid deuterium or superfluid helium
- **Fission energy** (fast) neutrons (0-14MeV)
 - close to 1 MeV (1.6×10^{-13} J), hence of ~ 14000 km/s
- **Fusion** neutrons, D-T fusion, 14.1MeV
- **Intermediate-energy** neutrons, ex. epithermal
- **High-energy** neutrons,
 - by particle accelerators or from cosmic rays

Interactions of Neutrons with Matter

Thermal neutron



(a) Thermal neutron cross section of some nuclei



(b) Nuclear reactions caused by thermal neutron in boron nucleus

Thermal neutron, or free neutron, larger effective cross-section (higher probability for interaction with nuclei)

$kT = 0.0253\text{eV}$ ($4.0 \times 10^{-21}\text{J}$) @RT,
if absorbed \rightarrow fusion, \rightarrow isotope \rightarrow SEE

Cross Section, Probability of the Reaction

- Probability, σ [counts cm²/particles]

$$\sigma = N_{\text{counts}} / (N/A) = N_{\text{counts}} / \Phi$$

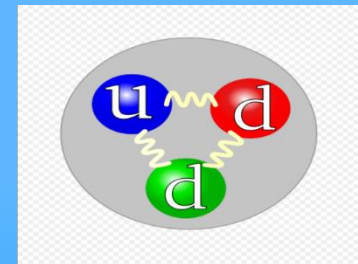
$$N_{\text{counts}} = N \left(\frac{\sigma}{A} \right) = \frac{N}{A} \sigma = \sigma \Phi$$

- Numbers of Damage

- In a SRAM study of the configuration memory, the cross-section is σ_{SEU} , then

$$N_{\text{counts}} = N_{\text{SEU}}$$

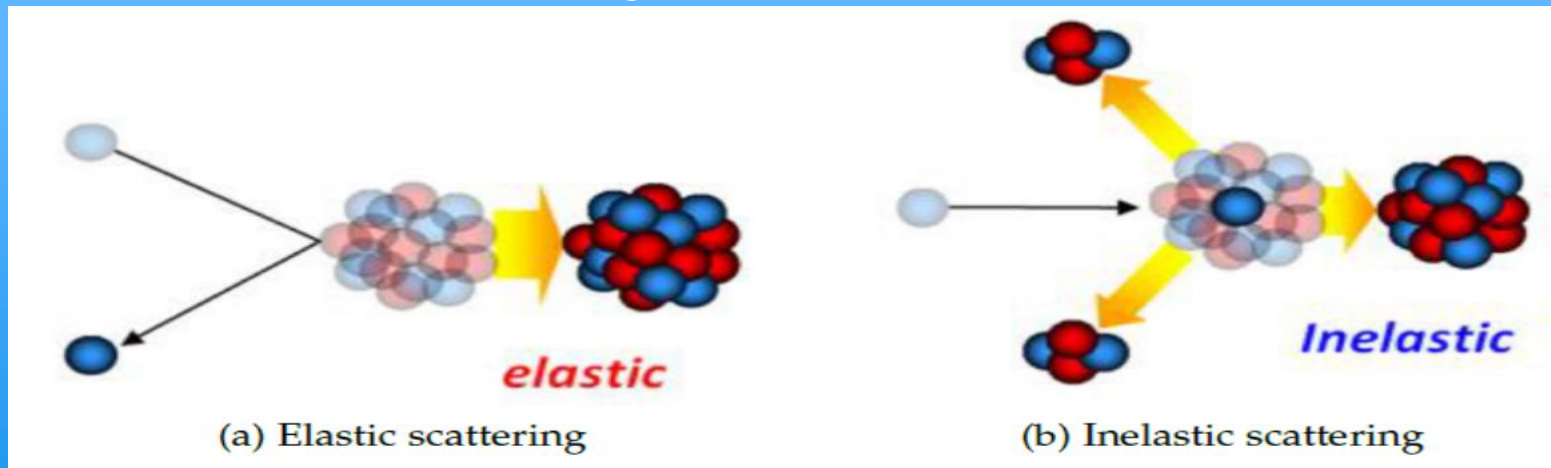
Neutron Flux



- Neutron *fluence*, $\Phi = \int_0^t \phi dt \left(\frac{\text{neutrons}}{\text{cm}^2 \text{s}} \right)$
- Natural neutron fluence
 - F_{star} : 10^5 - 10^{11} ; After a supernova, 10^{22} ;
 - in a thunderstorm $3 \cdot 10^2$ - $5 \cdot 10^2 \left(\frac{\text{neutrons}}{\text{cm}^2 \text{s}} \right)$
- Artificial neutron fluence
 - research reactor, nuclear power plant over 40yrs:
 - $3,5 \cdot 10^{19} \text{ n/cm}^2 \text{ (E>1MeV)}$
 - weaponry:

Interactions of Neutrons with Matter

Elastic and Inelastic Scatterings



Concerns:

For SRAM using 45nm process, the Q critical is about 1fC, while a 60eV neutron, in an elastic scattering process, can be a critical SEE.

$$E_{k,Si} = 0.13 E_{k,n}$$

Neutron Generation

Neutron generation for Biology Studies –

US 13,000 individuals receive measurable n doses

WW 1,000,000 airline crew members (1994)

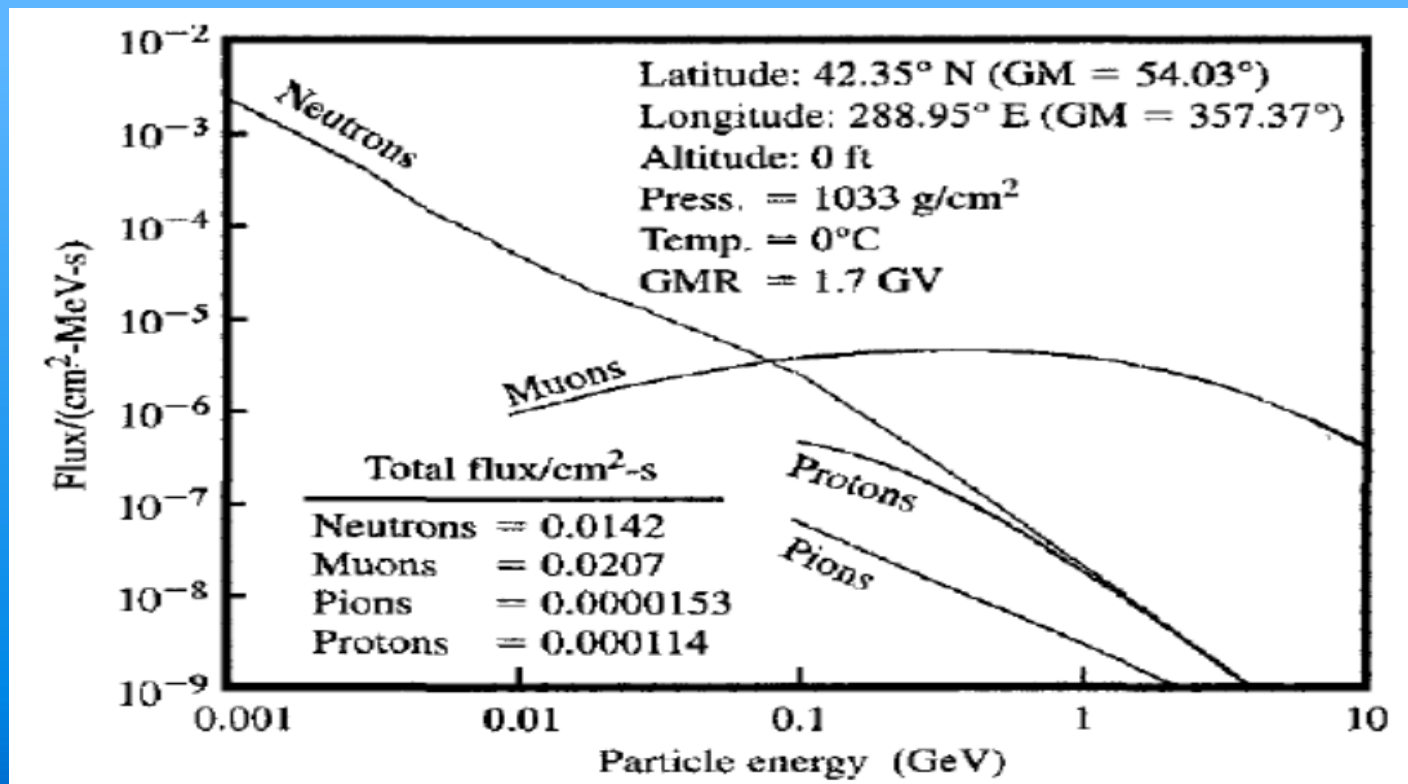
RBE of 10-100keV n, which has a range of 2um

For the interest of RadHard on IC?

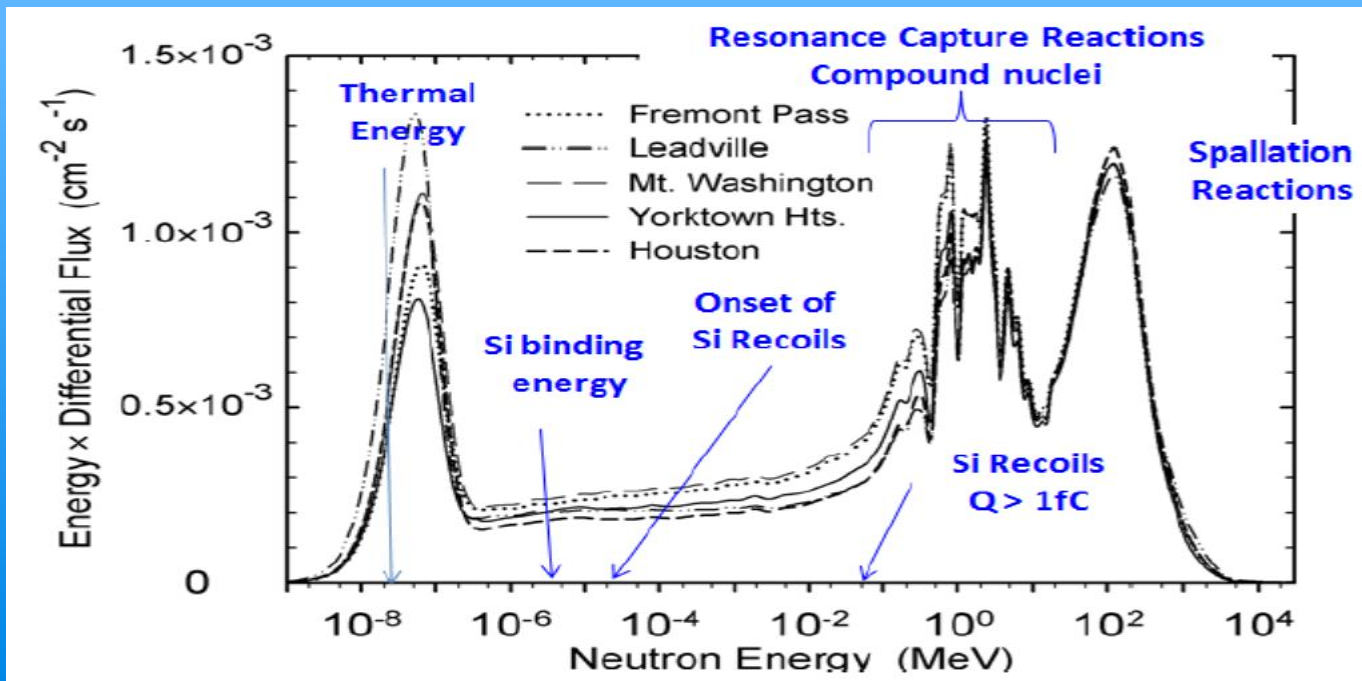
Incident P (1.92-2.00 MeV),

Reaction: ${}^7\text{Li}(p, n){}^7\text{Be}$ (threshold 1.88MeV)

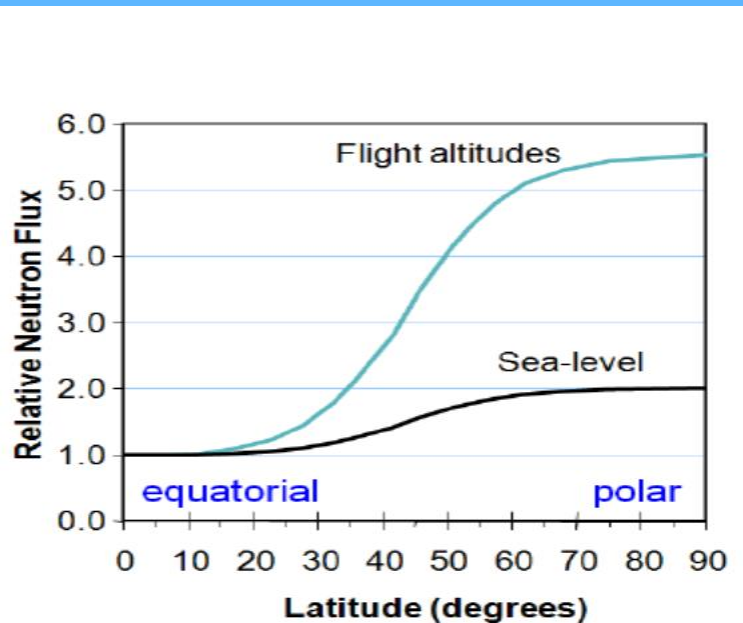
Neutrons in Terrestrial Particles



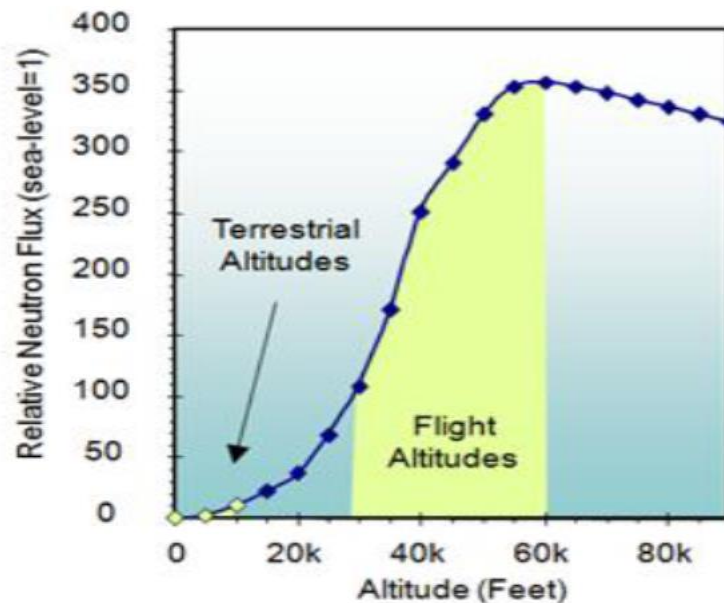
Neutron Flux at Known Geographical Sites



Neutron Flux at Various Latitude and Altitude








(a) Neutron flux variation with latitude



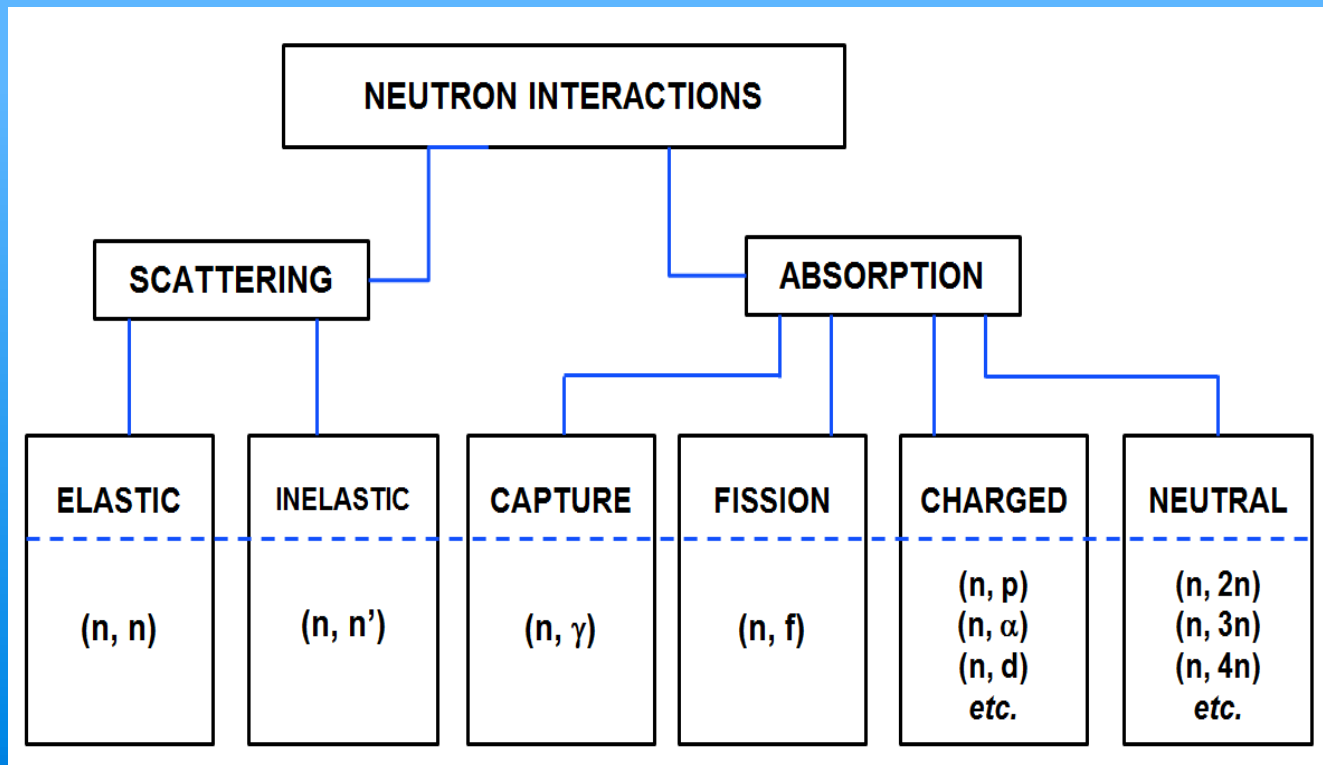
(b) Neutron flux variation with altitude

Neutron sources and types of interaction

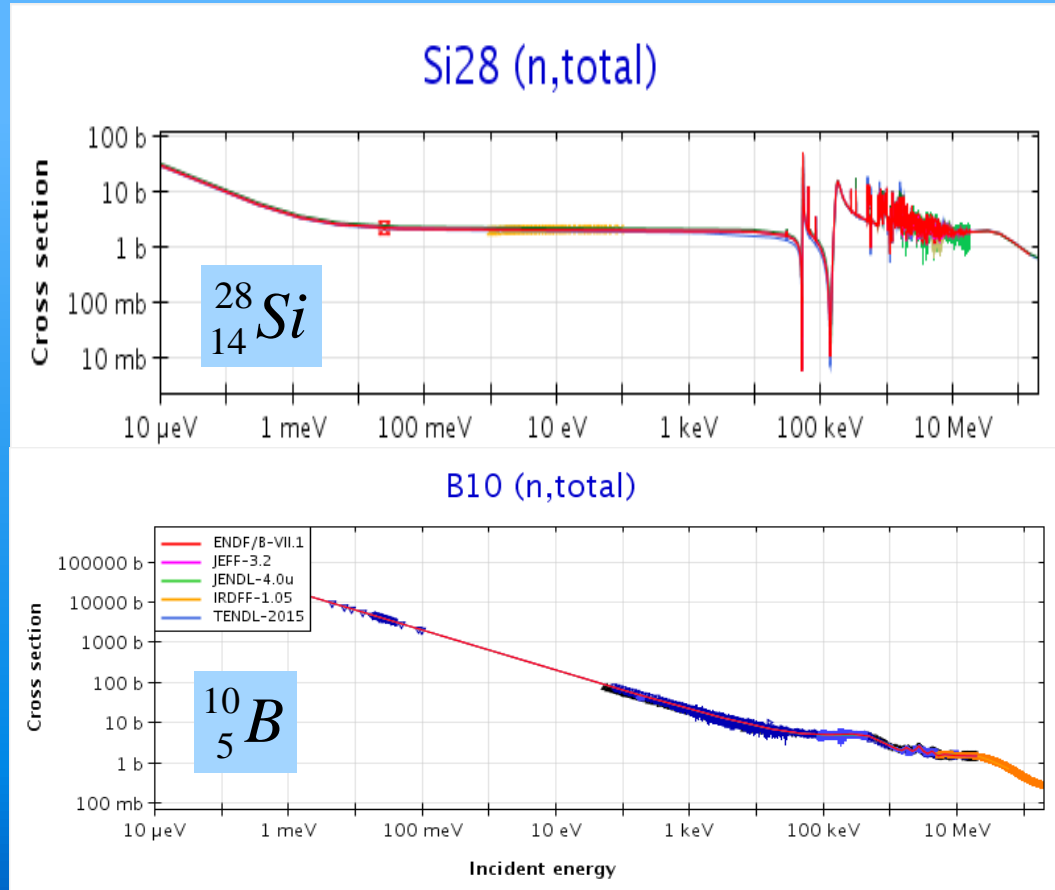
Neutron Types	Energy	Interactions		
Slow neutron	0 ~ 1 keV	 Diffraction	 Fission (n,f)	 Capture (n, γ),(n,p),(n, α)
<i>Cold neutron,</i>	≤ 0.002 eV			
<i>Thermal n,</i>	≈ 0.025 eV			
<i>Epithermal n,</i>	≥ 0.5 eV			
<i>Resonance n,</i>	1 eV ~ 1 keV			
Medium energy n	1 ~ 500 keV	 Elastic scattering (n,x)	 Inelastic scattering	
Fast neutron	0.5 ~ 10 MeV			
Very fast neutron	10 ~ 50 MeV			
Cosmic neutron	50MeV~10GeV			
Relativistic neutron	> 10 GeV			

Source: Chen & Hu, 2018, CSTIC

Neutron Interactions – Scattering and Absorption



Total neutron cross section (microscopic) σ



The macroscopic cross section Σ & the mean free path λ

Table 3: The macroscopic cross section and the mean free path of CMOS transistor compounds for 10 MeV neutrons

Compound	ρ	M	σ_1	σ_2	Σ_{comp}	λ
SiO ₂	2.27	60.08	1.90	1.32	0.103	9.709 _μ
GaAs	5.32	144.6	3.65	3.80	0.165	6.061 _μ
SiC	3.16	40.10	1.90	1.18	0.146	6.849 _μ
Si	2.329	28.08	1.90	N/A	0.095	10.53 _μ

Table 4: The macroscopic cross section and the mean free path of SiO₂ and Si at various neutron energies

E, MeV	0.001	0.01	0.1	1	10	100 _μ
SiO ₂ , Σ_{comp}	0.217	0.213	0.189	0.478	0.103	0.053 _μ
SiO ₂ , λ	4.608	4.695	5.291	2.092	9.709	18.87 _μ
Si, Σ_{comp}	0.097	0.087	0.050	0.230	0.095	0.055 _μ
Si, λ	10.31	11.49	20.00	4.348	10.53	18.18 _μ

RadHard in SoC Design

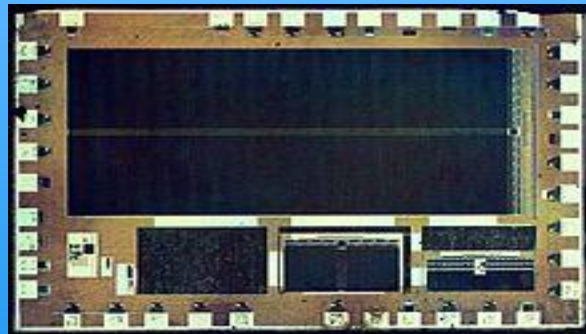
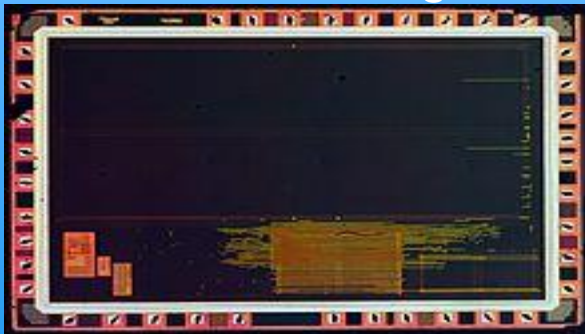


- SEE and RadHard: SEE/SEU, RadHard/TID/SP
- Cosmic Rays & Charged Particles: p , e , α , ions
- Cosmic Rays & Neutrons: cross-section, range, fluence
- **RadHard Remedies: TID, SEI**
- Discussion

Big Bang Higgs Boson Supernova Van Allen Belt

Radiation Hardening Technique

- After metalization etching

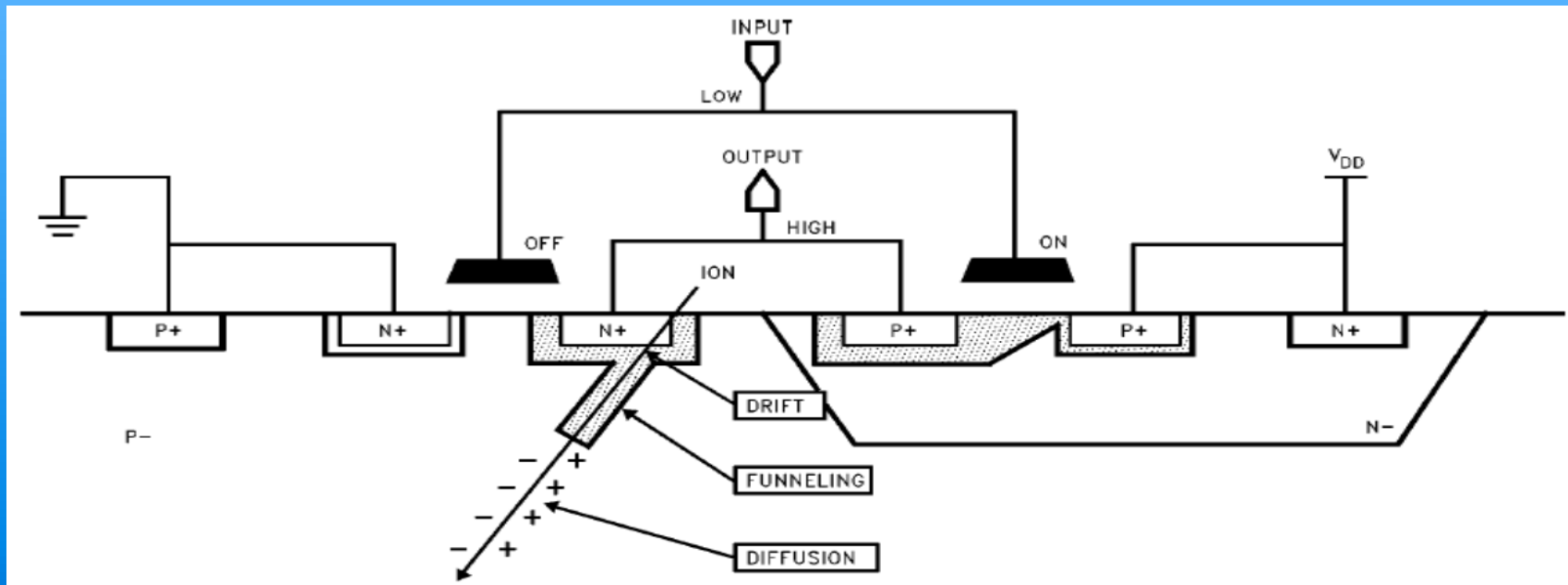


Radiation hardened die of the 1886VE10 microcontroller prior to (a), and after (b) a metalization etching process

Radiation Design Considerations in CMOS

By TI (1994)

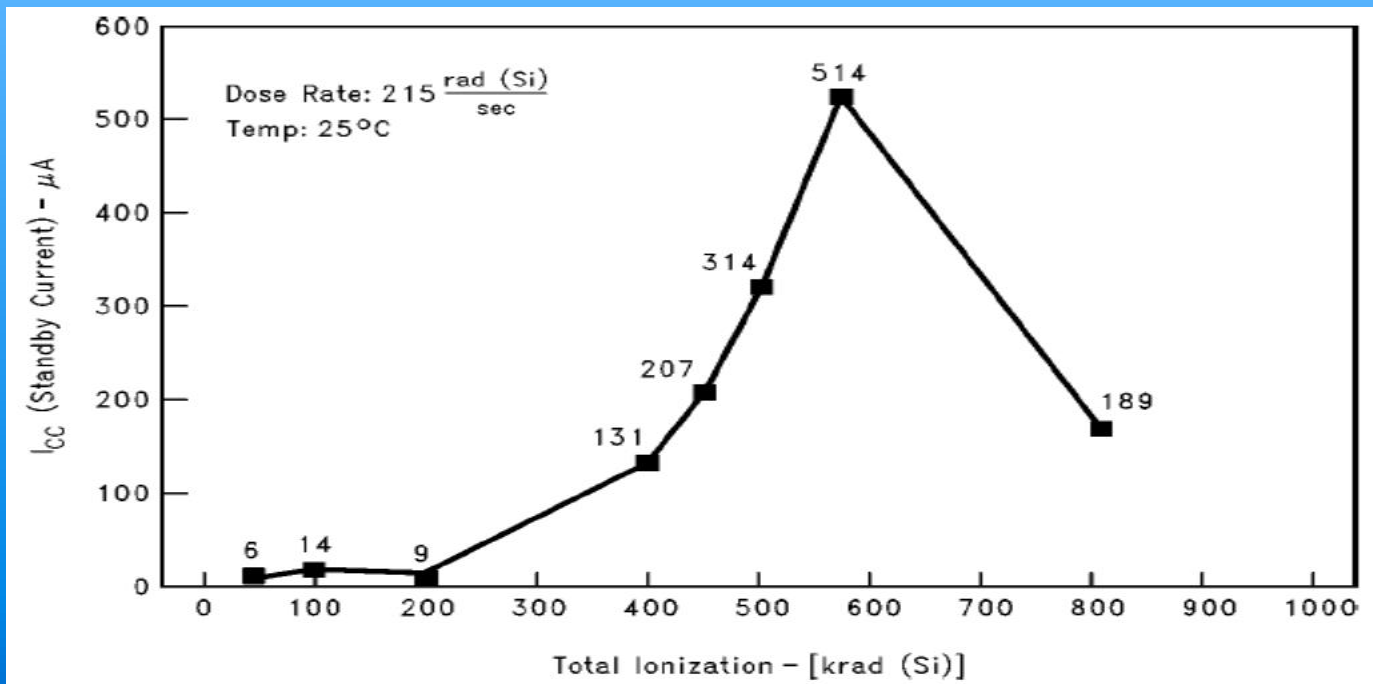
- SEU current (TI Copyright, 2011)



Radiation Design Considerations in CMOS

By TI (1994)

- I_{CC} (standby current) vs. TID



Radiation Resistant Computers

TABLE I SOI TECHNOLOGY ADVANTAGES BASED ON 0.25 μm SRAM TECHNOLOGY			
<i>Category</i>	<i>SEMATCH Estimation</i>	<i>Revenue Gain vs. Bulk CMOS</i>	<i>Latest Industry Benchmark</i>
Process steps	20% less process steps	Simpler well, isolation 6% revenue gain	Between 10–20% simpler
Mask counts	3 less masking steps	Simpler well, isolation	Between 1–3 fewer masks
Circuit density	1.3. improvement	Tighter isolation, latch up rules Additional 45% revenue gain	30% better
Performance	30% faster	Lower capacitance Additional 25% ASP* due to higher performance	Technology generation dependence
*ASP = Average Selling Price			

Heavy ions induced micro-dose is a serious concern in

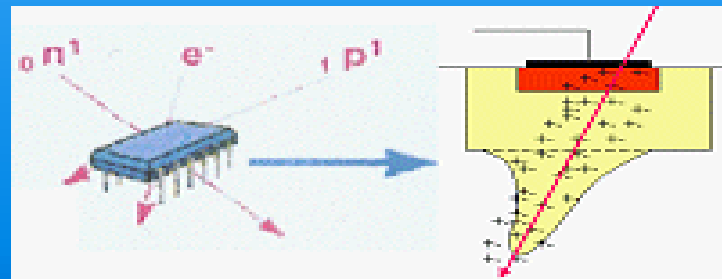
UTB SOI and
SOI FinFET

IR discharge current may cause

Automobile chip failure

Supercomputer chip error

10,000 chips are used, 10-20
faults/week



RadHard in SoC Design



- SEE and RadHard: SEE/SEU, RadHard/TID/SP
- Cosmic Rays & Charged Particles: p , e , α , ions
- Cosmic Rays & Neutrons: cross-section, range, fluence
- RadHard Remedies: TID, SOI
- Discussion

Big Bang Higgs Boson Supernova Van Allen Belt

Impact of ESD and Ionizing Radiation

- ESD has been studied on planar technologies of
 - UTB (ultra thin body) SOI
 - SOI FinFET, and
 - Bulk FinFET
- Heavy ions induced micro-dose is a serious concern in
 - UTB SOI and
 - SOI FinFET
- IR discharge current may cause
 - Automobile chip failure
 - Supercomputer chip error
 - 10,000 chips are used, 10-20 faults/week

TID and SEE wrt R and MFP

- Analyzed CDM/ESD
- TID and SET/SEE
 - Dimension of gate oxide
 - SEE by $I_{d,sat}$, g_m
- Calculated (for p, e, α) S, LET, R, MFP
 - SP | LET can be ambiguous
 - Range | MPF is more direct
 - Particle energy at track end is absorbed...
- More studies are needed
 - CDM of ESD
 - SEU & SET of SEE

Recent Applications on DRAM

- **Radiation Effects on DRAM/DDR_x [5/28/15]**

- SEU/ECC NASA, SEE-immunity, std for DARM using 25nm 100 krad

- **Increasing awareness of the need for SEE-immunity in**

- both aircraft and ground-level systems

- **The XR (eXtra Robust) ECC DRAMs are available in**

- DDR1, DDR2, DDR3 technologies.
- tests have passed on: 60/100/350krad, and continued (5/14/15)

- **For use in aircraft and high rel ground applications you should test in a spallation neutron source and in a thermal neutron beam. Sometimes this can be done together by using cadmium shielding and taking differences.**

- See IEC-TS62396 for details.

Increased Challenges in Shrinking Chips

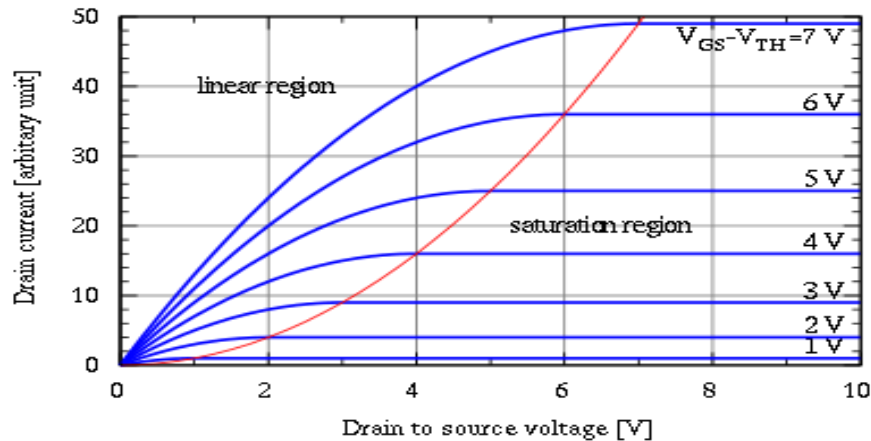
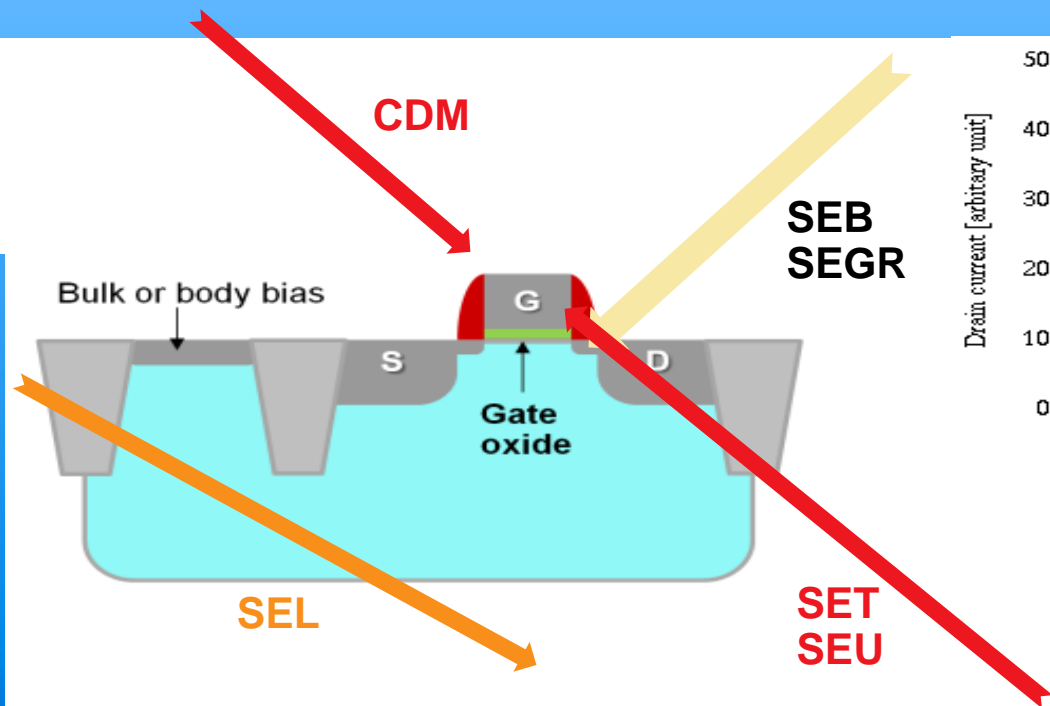
By John McHale (May 17, 2011)

- Military and Aerospace Electronics
- Aerospace and Defense
 - Technology Focus
 - Radiation and small components
 - Performance demands
 - Performance vs. rad-hard

August 2013
Volume 24, Issue 8



ESD and SEE on Bulk CMOS, FD-SOI, FinFET



SP/LET and D/D-rate of Ionizing Radiation

- SP (Stopping Power, MeV·cm²/mg)

$$S = k_1 \frac{Zz^2}{M_a \beta^2} \left[\ln \frac{2\mu\beta^2 \Delta}{I^2(1-\beta^2)} - \frac{(1-\beta^2)\Delta}{2\mu} - \beta^2 - 2\frac{C}{Z} - \delta \right]$$

$$L = S_{tot} \cdot \rho \quad (keV / \mu m)$$

- LET (Linear Energy Transfer, SP·ρ → LET)

$$D = \frac{\Delta E_D}{\Delta m} \quad (1Gy = 100rad = 1J / kg)$$

- Dose (or absorbed Dose)

$$\dot{D} = \frac{dD}{dt} = \frac{d}{dt} \left(\frac{\Delta E_D}{\Delta m} \right) \quad (1Gy / sec = 100rad / sec)$$

Neutrons on SEE

- Increased needs of DfX/Reliability in SoC
- Neutron flux *vs.* altitude (1-100x): applications
 - DC/BD/Supercomputing, ADAS, Aerotronics
- Neutron energy *w.r.t.* interaction types
 - Combined SEE/SEU in materials
- Fluence and SER (SEU) in I/O, RAM
 - Advanced process

Appendix for Neutron Calculation

Diffraction Cross-section, Range, Mean Free Path, Fluence

- Neutron diffraction (elastic scattering), the *Bragg's law*,

$$n\lambda = 2d \sin \theta$$

- The total cross section (*microscopic*), $\sigma_T = \sigma_S + \sigma_A$
- The *Ramsauer Model*, $\sigma_T(E) = 2\pi[(R + \lambda_r(E))^2 (1 - \alpha \cos \beta)]$
- The *macroscopic* cross-section Σ_{comp}

$$\Sigma_{comp} = \sigma_i N_i, \quad N_i = \rho N_a n_i / M$$

- The mean free path λ , $\lambda = 1 / \Sigma$
- The temperature impact of neutrons, $\sigma_T = \sigma_0 (T_0 / T)^{1/2}$
- The flux I_2 can be calculated at altitude A_2

$$I_2 = I_1 \exp[(A_1 - A_2) / L_n]$$

- **Chen, C.-Z.** and Hu, D.Y., 2018, Analysis of Affecting Factors in Neutron Interactions with Gate Oxide in CMOS Transistors. China Semicon. Tech. Int. Conf. (CSTIC, March 11-12, 2018, Shanghai), to be published.
- **Chen, C.-Z.** and Hu, D.Y., 2017, Geometry Effect with Respect to ESD and Radiative Charged Particles in SoC. China Semicon. Tech. Int. Conf. (CSTIC, March 12-13, 2017, Shanghai.) **IEEE Conf. Pub.**, <http://ieeexplore.ieee.org/document/7919894/>, pp.1-3.
(DOI: [10.1109/CSTIC.2017.7919894](https://doi.org/10.1109/CSTIC.2017.7919894))
- **Chen, C.-Z.** and Hu, D.Y., 2016, Analysis of ESD Effect and Radiation Damage in SoC Design, Semicond. Tech. Inte. Conf. (CSTIC, March 13-14, Shanghai), 2016 China. Page(s): 1-4, Accepted.
- **Chen, C.-Z.** and Watt, D.E., 1986, Biophysical mechanism of radiation damage to mammalian cells by x and γ -rays. *Int. J. Radiat. Biol.* **49**, 131-142.